# YIBO LIU

buaayorklau@gmail.com Personal Webpage | Google Scholar https://github.com/York-SDCNLab | LinkedIn

### RESEARCH INTEREST

My research interest lies in the domain of computer vision and generative AI.

- I began pursuing a Ph.D. degree in January 2020 with a focus on robotic vision, and during that time, my research centered on the localization and navigation of robots (RA-L2022, IROS2022, TIM2024).
- Since 2022, my research primarily involved in-the-wild object 3D reconstruction and 3D content (NeRFs/3D Gaussians Splatting) generation, which provides objects for the simulation in autonomous driving. I had one first-author paper, MV-DeepSDF, accepted to ICCV2023. Moreover, I was the Top-3 winner of OmniObject3D challenge at ICCV2023 [report] .
- Since mid-2023, I have been conducting research on LLM, Vision Question Answering (VQA), and Diffusion Models intending to generate photorealistic 2D/3D assets. I had one first-author paper, VQA-Diff, accepted to ECCV2024.

### RESEARCH EXPERIENCE

### Noah's Ark Lab, Huawei Canada

Feb<br/> 2022 - present

Part-time Research Intern. Mentor: Yuan Ren

Toronto, Canada

- Focused on in-the-wild object reconstruction and image/text-to-3D content generation under the background of simulation in the autonomous driving industry. My research involved Visual Question Answering models, Diffusion models, NeRFs, and Gaussian Splatting.
- Contribution:

VQA-Diff: Exploiting VQA and Diffusion for Zero-Shot Image-to-3D Vehicle Asset Generation in Autonomous Driving (first author, ECCV2024).

MV-DeepSDF: Implicit Modeling with Multi-Sweep Point Clouds for 3D Vehicle Reconstruction in Autonomous Driving (first author, ICCV2023, DOI).

Top-3 winner of OmniObject3D challenge (Co-first author, ArXiv, NeurIPS 2024 Workshop on Symmetry and Geometry in Neural Representations).

### York University

Jan 2020 – present

Research Assistant. Supervisor: Prof. Jinjun Shan.

Toronto, Canada

- Focused on robotic vision which involved camera/LiDAR-based perception, SLAM, and navigation.
- Contribution:

Intensity Image-based LiDAR Fiducial Marker System (first author, **RA-L2022**, DOI, Github **55** stars) . Application of Ghost-DeblurGAN to Fiducial Marker Detection (first author, **IROS2022**, DOI, Github **31** stars). Mapping and Localization using LiDAR Fiducial Markers (first author, submitted to **TIM**, Github **110** stars).

### **EDUCATION**

Master

### York University, Lassonde School of Engineering

Toronto, Canada

Ph.D. Student. Supervisor:Prof. Jinjun Shan.

Jan 2020-present

• Scholarship:

Academic Excellence Fund (maximum amount, 2022, 2023).

York Graduate Scholarship (2020).

## BeiHang University, School of Aeronautic Science and Engineering

Beijing, China Sep 2017-Jan 2020

• Scholarship:

First-class Academic Merit (Top 3%).

Outstanding Science and Technology Competition Medal of May 4th (5 out of 22,000).

Ministry of Industry and Information Technology Innovation and Entrepreneurship (10 out of 40,000)

### BeiHang University, School of Aeronautic Science and Engineering

Bachelor

Beijing, China Sep 2013-June 2017

• Scholarship: Outstanding Graduate (Top 5%); Outstanding Student Cadres

### SELECTED Publication & Award List

### Publication

- [1] Liu Y\*, Yang Z\*, Wu G, Ren Y, Lin K, Liu B, Liu Y, Shan J. "VQA-Diff: Exploiting VQA and Diffusion for Zero-Shot Image-to-3D Vehicle Asset Generation in Autonomous Driving", in Proc. European Conference on Computer Vision (ECCV), 2024.
- [2] Liu Y, Zhu K, Wu G, Ren Y, Liu B, Liu Y, Shan J. "MV-DeepSDF: Implicit Modeling with Multi-Sweep Point Clouds for 3D Vehicle Reconstruction in Autonomous Driving", in Proc. IEEE/CVF International Conference on Computer Vision (ICCV), 2023, pp. 8306-8316.
- [3]Yang Z\*, Liu Y\*, Wu G, Cao T, Ren Y, Liu Y, Liu B. "Learning Effective NeRFs and SDFs Representations with 3D Generative Adversarial Networks for 3D Object Generation". **NeurIPS 2024** Workshop on Symmetry and Geometry in Neural Representations. Top-3 winner of **ICCV 2023** OmniObject3D Challenge.
- [4] Liu Y, Schofield H, Shan J. "Intensity Image-Based LiDAR Fiducial Marker System", in IEEE Robotics and Automation Letters (RA-L), vol. 7, no. 3, pp. 6542-6549, July 2022, doi: 10.1109/LRA.2022.3174971.
- [5]**Liu Y**, Schofield H, Shan J. "Application of Ghost-DeblurGAN to Fiducial Marker Detection", in Proc. IEEE/RSJ International Conference on Intelligent Robots and Systems (**IROS**), 2022, pp. 6827-6832, doi: 10.1109/IROS47612.2022.9981701.
- [6] Liu Y, Schofield H, Shan J. "Navigation of a Self-Driving Vehicle Using One Fiducial Marker", in Proc. IEEE International Conference on Multisensor Fusion and Integration for Intelligent Systems (MFI), 2021, pp. 1-6, doi: 10.1109/MFI52462.2021.9591194.
- [7]Zhang S, Shan J and **Liu Y** "Approximate Inference Particle Filtering for Mobile Robot SLAM," in IEEE Transactions on Automation Science and Engineering, doi: 10.1109/**TASE**.2024.3475735
- [8]Zhang S, Shan J and **Liu Y**. "Variational Bayesian Estimator for Mobile Robot Localization With Unknown Noise Covariance," in IEEE/ASME Transactions on Mechatronics, vol. 27, no. 4, pp. 2185-2193, Aug. 2022, doi: 10.1109/**T-MECH**.2022.3161591.

### Award

- [1] Top-3 winner of OmniObject3D Challenge at ICCV2023 (3D Object Generation Task).
- [2] The first prize, 15th 'Challenge Cup' National Science and Technology College of extra-curricular academic competition works, second author
- [3] Excellent Grade, 9th National College Students Innovation and Entrepreneurship Training Plan, initiator

#### Technical Reviewer

- International Conference on Learning Representations (ICLR), Neural Information Processing Systems (NeurIPS)
- IEEE Robotics and Automation Letters (RA-L), IEEE Robotics and Automation Magazine (RA-M)
- IEEE International Conference on Robotics and Automation (ICRA), IEEE/RSJ International Conference on Intelligent Robots and Systems (IROS), Artificial Intelligence and Statistics (AISTATS), IEEE/ASME International Conference on Advanced Intelligent Mechatronics (AIM)
- IEEE Transactions on Instrumentation and Measurement (TIM)
- IEEE Transactions on Industrial Electronics (TIE)